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| • | Inputs Are TTL-Voltage Compatible<br>Speed of Bipolar F, AS, and S, With<br>Significantly Reduced Power | CD54ACT153 F PACKAGE<br>CD74ACT153 E OR M PACKAGE<br>(TOP VIEW) |                   |     |  |  |  |  |
|---|---|---|-------------------|-----|--|--|--|--|
|   | Consumption   |   | $   \nabla_{16} $ | Vcc |  |  |  |  |
| • | Balanced Propagation Delays   | ВП2   | 15                | 2G  |  |  |  |  |
| • | ±24-mA Output Drive Current   | 1C3 🛛 3   | 14                | А   |  |  |  |  |
|   | <ul> <li>Fanout to 15 F Devices</li> </ul>  | 1C2 [ 4   | 13                | 2C3 |  |  |  |  |
| • | SCR-Latchup-Resistant CMOS Process  | 1C1 [ 5   | 12                | 2C2 |  |  |  |  |
|   | and Circuit Design  | 1C0 🛛 6   | 11                | 2C1 |  |  |  |  |
| • | Exceeds 2-kV ESD Protection Per   | 1Y 🛛 7  | 10                | 2C0 |  |  |  |  |
|   | MIL-STD-883, Method 3015  | GND [8  | 9                 | 2Y  |  |  |  |  |

#### description/ordering information

Each of these data selectors/multiplexers contains inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe ( $\overline{G}$ ) inputs are provided for each of the two 4-line sections.

| TA             | PACKA    | AGE†          | ORDERABLE<br>PART NUMBER | TOP-SIDE<br>MARKING |
|----------------|----------|---------------|--------------------------|---------------------|
|                | PDIP – E | Tube          | CD74ACT153E              | CD74ACT153E         |
| –55°C to 125°C | SOIC – M | Tube          | CD74ACT153M              | ACT153M             |
| -55°C 10 125°C | 301C - M | Tape and reel | CD74ACT153M96            | ACTION              |
|                | CDIP – F | Tube          | CD54ACT153F3A            | CD54ACT153F3A       |

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

|      | INPUTS |    |    |    |    |   |   |  |  |  |  |  |  |
|------|--------|----|----|----|----|---|---|--|--|--|--|--|--|
| SELI | ЕСТ‡   |    | DA | TA |    | G |   |  |  |  |  |  |  |
| В    | Α      | C0 | C1 | C2 | C3 | G | • |  |  |  |  |  |  |
| Х    | Х      | Х  | Х  | Х  | Х  | Н | L |  |  |  |  |  |  |
| L    | L      | L  | Х  | Х  | Х  | L | L |  |  |  |  |  |  |
| L    | L      | н  | Х  | Х  | Х  | L | н |  |  |  |  |  |  |
| L    | н      | Х  | L  | Х  | Х  | L | L |  |  |  |  |  |  |
| L    | н      | Х  | Н  | Х  | Х  | L | н |  |  |  |  |  |  |
| н    | L      | Х  | Х  | L  | Х  | L | L |  |  |  |  |  |  |
| н    | L      | Х  | Х  | н  | Х  | L | н |  |  |  |  |  |  |
| н    | Н      | Х  | Х  | Х  | L  | L | L |  |  |  |  |  |  |
| н    | Н      | Х  | Х  | Х  | Н  | L | Н |  |  |  |  |  |  |

#### FUNCTION TABLE

<sup>‡</sup>Select inputs A and B are common to both sections.



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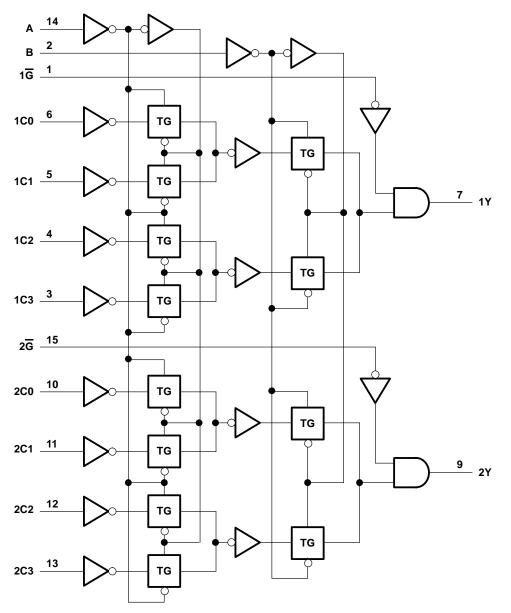
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### logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature range<sup>†</sup>

| Supply voltage range, V <sub>CC</sub>  | –0.5 V to 6 V  |
|--|----------------|
| Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)                                   |                |
| Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1) | ±50 mA         |
| Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$  | ±50 mA         |
| Continuous current through V <sub>CC</sub> or GND  | ±100 mA        |
| Package thermal impedance, $\theta_{JA}$ (see Note 2): E package   |                |
| M package  | 73°C/W         |
| Storage temperature range, T <sub>stg</sub>  | –65°C to 150°C |

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

|                     |                                    | T <sub>A</sub> = | T <sub>A</sub> = 25°C |     | C to<br>°C | –40°<br>85° | UNIT |      |
|---------------------|------------------------------------|------------------|-----------------------|-----|------------|-------------|------|------|
|                     |                                    | MIN              | MAX                   | MIN | MAX        | MIN         | MAX  |      |
| Vcc                 | Supply voltage                     | 4.5              | 5.5                   | 4.5 | 5.5        | 4.5         | 5.5  | V    |
| VIH                 | High-level input voltage           | 2                |                       | 2   |            | 2           |      | V    |
| VIL                 | Low-level input voltage            |                  | 0.8                   |     | 0.8        |             | 0.8  | V    |
| VI                  | Input voltage                      | 0                | VCC                   | 0   | VCC        | 0           | VCC  | V    |
| Vo                  | Output voltage                     | 0                | VCC                   | 0   | VCC        | 0           | VCC  | V    |
| ЮН                  | High-level output current          |                  | -24                   |     | -24        |             | -24  | mA   |
| IOL                 | Low-level output current           |                  | 24                    |     | 24         |             | 24   | mA   |
| $\Delta t/\Delta v$ | Input transition rise or fall rate |                  | 10                    |     | 10         |             | 10   | ns/V |

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                  | TEST CON                            | IDITIONS                           | Vcc            | T <sub>A</sub> = 25°C |      | –55°C to<br>125°C |      | –40°C to<br>85°C |      | UNIT |  |  |
|----------------------------|-------------------------------------|------------------------------------|----------------|-----------------------|------|-------------------|------|------------------|------|------|--|--|
|                            |                                     |                                    |                | MIN                   | MAX  | MIN               | MAX  | MIN              | MAX  |      |  |  |
|                            |                                     | I <sub>OH</sub> = -50 μA           | 4.5 V          | 4.4                   |      | 4.4               |      | 4.4              |      |      |  |  |
| VOH                        | $\lambda = \lambda = 0$             | I <sub>OH</sub> = -24 mA           | 4.5 V          | 3.94                  |      | 3.7               |      | 3.8              |      | V    |  |  |
|                            | $V_{I} = V_{IH} \text{ or } V_{IL}$ | I <sub>OH</sub> = -50 mA†          | 5.5 V          |                       |      | 3.85              |      |                  |      | V    |  |  |
|                            |                                     | I <sub>OH</sub> = -75 mA†          | 5.5 V          |                       |      |                   |      | 3.85             |      |      |  |  |
|                            | VI = VIH or VIL                     | IOL = 50 μA                        | 4.5 V          |                       | 0.1  |                   | 0.1  |                  | 0.1  |      |  |  |
|                            |                                     | I <sub>OL</sub> = 24 mA            | 4.5 V          |                       | 0.36 |                   | 0.5  |                  | 0.44 | _ ∨  |  |  |
| VOL                        |                                     | $I_{OL} = 50 \text{ mA}^{\dagger}$ | 5.5 V          |                       |      |                   | 1.65 |                  |      |      |  |  |
|                            |                                     | $I_{OL} = 75 \text{ mA}^{\dagger}$ | 5.5 V          |                       |      |                   |      |                  | 1.65 |      |  |  |
| l                          | $V_I = V_{CC} \text{ or } GND$      |                                    | 5.5 V          |                       | ±0.1 |                   | ±1   |                  | ±1   | μA   |  |  |
| ICC                        | $V_I = V_{CC} \text{ or } GND,$     | IO = 0                             | 5.5 V          |                       | 8    |                   | 160  |                  | 80   | μA   |  |  |
| $\Delta I_{CC}^{\ddagger}$ | $V_{I} = V_{CC} - 2.1 V$            |                                    | 4.5 V to 5.5 V |                       | 2.4  |                   | 3    |                  | 2.8  | mA   |  |  |
| Ci                         |                                     |                                    |                |                       | 10   |                   | 10   |                  | 10   | pF   |  |  |

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

<sup>‡</sup>Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

#### ACT INPUT LOAD TABLE

| INPUT  | UNIT LOAD |
|--------|-----------|
| A or B | 1         |
| С      | 1         |
| G      | 0.47      |

Unit Load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

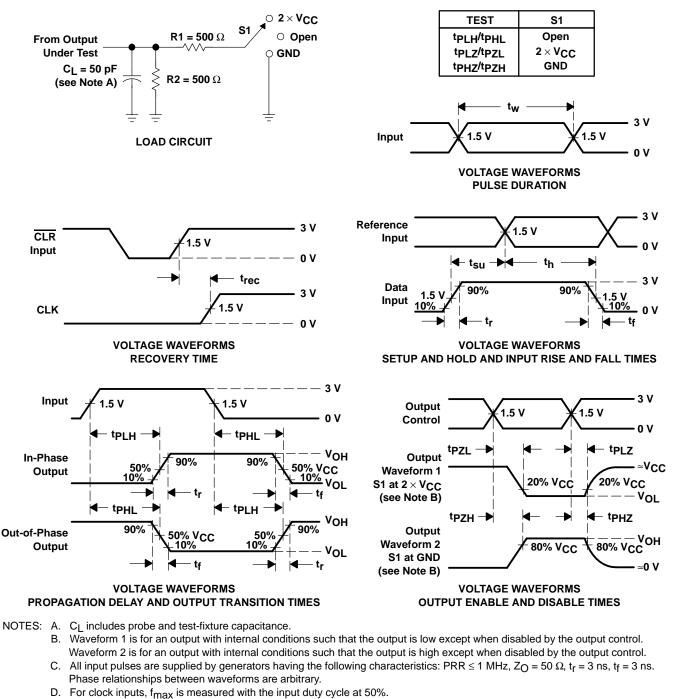
| PARAMETER        | FROM<br>(INPUT) | ТО<br>(OUTPUT) | –55°(<br>125 |      | –40°(<br>85° | UNIT |     |
|------------------|-----------------|----------------|--------------|------|--------------|------|-----|
|                  | (INFOT)         | (001101)       | MIN          | MAX  | MIN          | MAX  |     |
| <sup>t</sup> PLH | A or B          | ~              | 5.5          | 22   | 5.7          | 20   | ns  |
| <sup>t</sup> PHL |                 | •              | 5.5          | 22   | 5.7          | 20   | 115 |
| <sup>t</sup> PLH | Any C           | ~              | 4.5          | 18   | 4.6          | 16.4 | ns  |
| <sup>t</sup> PHL |                 | •              | 4.5          | 18   | 4.6          | 16.4 | 115 |
| <sup>t</sup> PLH | G               | ~              | 3.2          | 12.6 | 3.2          | 11.5 |     |
| <sup>t</sup> PHL | 0               | T              | 3.2          | 12.6 | 3.2          | 11.5 | ns  |

### operating characteristics, $T_A = 25^{\circ}C$

|     | PARAMETER                     |    |    |  |  |  |
|-----|-------------------------------|----|----|--|--|--|
| Cpd | Power dissipation capacitance | 93 | pF |  |  |  |



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### PARAMETER MEASUREMENT INFORMATION

- E. The outputs are measured one at a time with one input transition per measurement.
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G.  $t_{PZI}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





#### PACKAGING INFORMATION

| Orderable Device | Status  | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)     | Lead finish/<br>Ball material | MSL Peak Temp      | Op Temp (°C) | Device Marking<br>(4/5) | Samples |
|------------------|---------|--------------|--------------------|------|----------------|---------------------|-------------------------------|--------------------|--------------|-------------------------|---------|
|                  | (.)     |              | 0                  |      |                | (=)                 | (6)                           | (0)                |              | (,                      |         |
| CD54ACT153F3A    | ACTIVE  | CDIP         | J                  | 16   | 1              | Non-RoHS<br>& Green | SNPB                          | N / A for Pkg Type | -55 to 125   | CD54ACT153F3A           | Samples |
| CD74ACT153E      | ACTIVE  | PDIP         | Ν                  | 16   | 25             | RoHS & Green        | NIPDAU                        | N / A for Pkg Type | -55 to 125   | CD74ACT153E             | Samples |
| CD74ACT153M      | LIFEBUY | SOIC         | D                  | 16   | 40             | RoHS & Green        | NIPDAU                        | Level-1-260C-UNLIM | -55 to 125   | ACT153M                 |         |
| CD74ACT153M96    | ACTIVE  | SOIC         | D                  | 16   | 2500           | RoHS & Green        | NIPDAU                        | Level-1-260C-UNLIM | -55 to 125   | ACT153M                 | Samples |
| CD74ACT153NSR    | ACTIVE  | SO           | NS                 | 16   | 2000           | RoHS & Green        | NIPDAU                        | Level-1-260C-UNLIM | -55 to 125   | ACT153M                 | Samples |

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF CD54ACT153, CD74ACT153 :

- Catalog : CD74ACT153
- Military : CD54ACT153

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

STRUMENTS

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal |                 |                    |    |      |                          |                          |            |            |            |            |           |                  |
|-----------------------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device                      | Package<br>Type | Package<br>Drawing |    | SPQ  | Reel<br>Diameter<br>(mm) | Reel<br>Width<br>W1 (mm) | A0<br>(mm) | B0<br>(mm) | K0<br>(mm) | P1<br>(mm) | W<br>(mm) | Pin1<br>Quadrant |
| CD74ACT153M96               | SOIC            | D                  | 16 | 2500 | 330.0                    | 16.4                     | 6.5        | 10.3       | 2.1        | 8.0        | 16.0      | Q1               |
| CD74ACT153NSR               | SO              | NS                 | 16 | 2000 | 330.0                    | 16.4                     | 8.2        | 10.5       | 2.5        | 12.0       | 16.0      | Q1               |



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# PACKAGE MATERIALS INFORMATION

9-Aug-2022



\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74ACT153M96 | SOIC         | D               | 16   | 2500 | 340.5       | 336.1      | 32.0        |
| CD74ACT153NSR | SO           | NS              | 16   | 2000 | 356.0       | 356.0      | 35.0        |

### TEXAS INSTRUMENTS

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### TUBE



### - B - Alignment groove width

#### \*All dimensions are nominal

| Device      | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | Τ (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| CD74ACT153E | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |
| CD74ACT153E | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |
| CD74ACT153M | D            | SOIC         | 16   | 40  | 507    | 8      | 3940   | 4.32   |

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



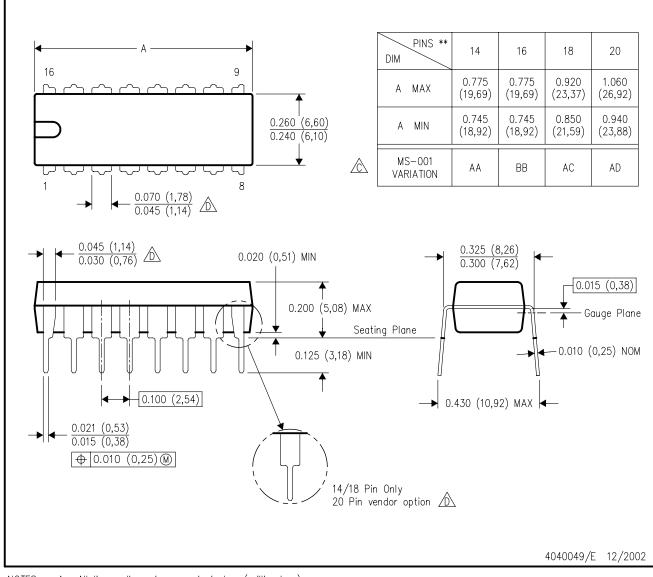
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



# **NS0016A**



# **PACKAGE OUTLINE**

SOP - 2.00 mm max height

SOP



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- Per ASME Y14.5M.
   This drawing is subject to change without notice.
   This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



# NS0016A

# **EXAMPLE BOARD LAYOUT**

### SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# NS0016A

# **EXAMPLE STENCIL DESIGN**

### SOP - 2.00 mm max height

SOP



NOTES: (continued)

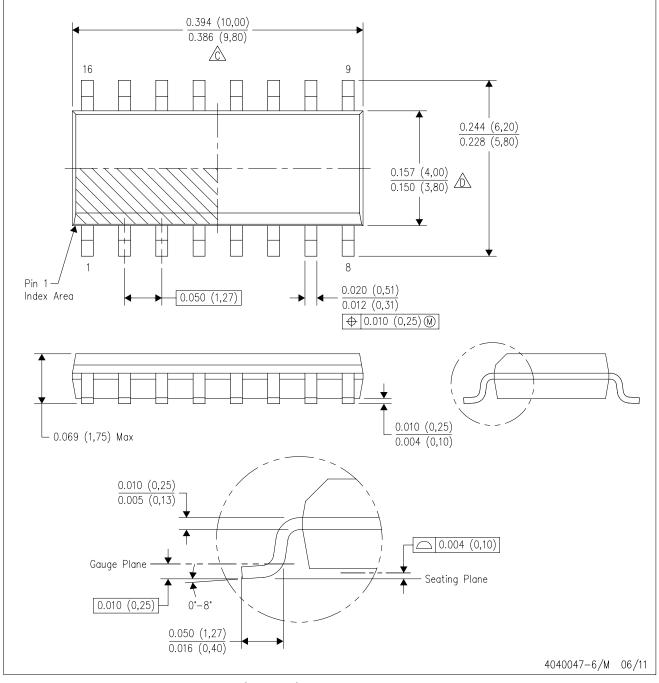
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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